

Specification for Approval

Date: 2024/08/30

Customer : Blume

TAI-TECH P/N: HPC3015BM-Series

CUSTOMER P/N:

DESCRIPTION:

QUANTITY: pcs

REMARK:

Customer Approval Feedback

- ☐ 西北臺慶科技股份有限公司
TAI-TECH Advanced Electronics Co., Ltd
Headquarter:
NO.1 YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI,
TAO-YUAN HSIEN, TAIWAN, R.O.C.
TEL: +886-3-4641148 FAX: +886-3-4643565
<http://www.tai-tech.com.tw>
E-mail: sales@tai-tech.com.tw
- ☐ 臺慶精密電子(昆山)有限公司
TAI-TECH ADVANCED ELECTRONICS(KUNSHAN) CO., LTD
SHINWHA ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN,
JIANG-SU, CHINA
TEL: +86-512-57619396 FAX: +86-512-57619688
E-mail: sales@tai-tech.cn

Sales Dep.

APPROVED	CHECKED
Gary	Gary

R&D Center

APPROVED	CHECKED	DRAWN
Sky Luo	Mr.Liang	Xu yaoyao

- 慶邦電子元器件(泗洪)有限公司
TAIPAQ ELECTRONICS (SIHONG) CO., LTD
THE SOUTH HANGZHOU ROAD AND THE EAST JIAN SHE BEI
ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY,
JIANGSU PROVINCE, P.R. CHINA.
TEL: +86-527-88601191 FAX: +86-527-88601190
E-mail: sales@taipaq.cn

Power Inductor**HPC3015BM-Series****ECN HISTORY LIST**

REV	DATE	DESCRIPTION	APPROVED	CHECKED	DRAWN
1.0	24/08/30	New Issue	Sky Luo	Mr.Liang	Xu yaoyao
備 註					

Power Inductor

1. Features

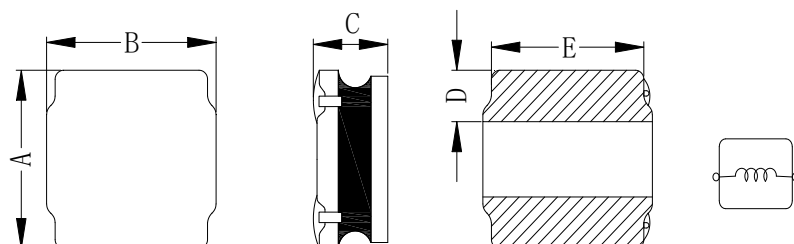
1. This specification applies Low Profile Power Inductors.
2. 100% Lead(Pb)-Free & Halogen-Free and RoHS compliant.
3. Operating temperature : -40~+125℃ (Including self - temperature rise)



2. Applications

Commercial applications

3. Dimension



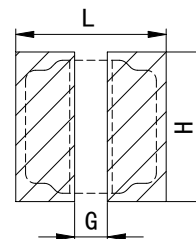
A	B	C	D	E
3.0±0.2	3.0±0.2	1.3±0.2	0.9±0.3	2.7±0.3

Unit:mm

Note: 1. A, B Size may slightly bigger than ferrite core dimension after epoxy sealing, but not exceed 0.1mm.

2. Component height may slight higher than C size and not exceed 0.1mm, and will be lower after reflow soldering

Recommended Land pattern



L	G	H
3.5	0.9	3.5

Note: 1. The above PCB layout reference only.
2. Recommend solder paste thickness at 0.15mm and above.

4. Part Numbering

HPC **3015** **BM** - **2R2** **M**

A B C D E

A: Series

B: Dimension

C: Lead Free

E: Inductance

2R2=2.20uH

F: Inductance Tolerance

K=± 10%, L=± 15%, M=± 20%, Y=± 30%.

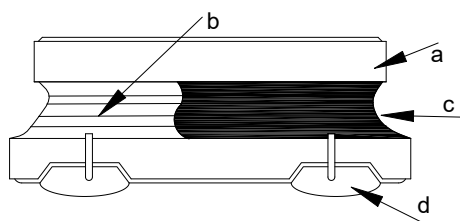
5. Specification

Part Number	Inductance (uH) $\pm 20\%$ @ 0 A DC	I rms (A)		I sat (A)		DCR (m Ω)	
		Typ	Max	Typ	Max	Typ	Max
HPC3015BM-R24M	0.24	5.00	4.50	6.00	5.50	13	16
HPC3015BM-R47M	0.47	3.70	3.30	4.30	4.00	18	22
HPC3015BM-R68M	0.68	3.50	3.20	3.80	3.50	23	28
HPC3015BM-1R0M	1.00	3.00	2.70	3.00	2.70	30	36
HPC3015BM-1R5M	1.50	2.70	2.50	2.40	2.10	36	43
HPC3015BM-2R2M	2.20	2.50	2.30	2.10	1.90	60	72
HPC3015BM-3R3M	3.30	2.20	2.00	1.70	1.50	80	96
HPC3015BM-4R7M	4.70	1.90	1.70	1.50	1.30	112	134
HPC3015BM-5R6M	5.60	1.80	1.60	1.40	1.20	135	162
HPC3015BM-6R8M	6.80	1.70	1.50	1.30	1.10	172	206
HPC3015BM-100M	10.0	1.50	1.30	1.00	0.90	220	264
HPC3015BM-150M	15.0	1.20	1.00	0.85	0.72	310	372
HPC3015BM-180M	18.0	1.10	0.92	0.73	0.65	380	456
HPC3015BM-220M	22.0	1.00	0.85	0.68	0.59	450	540
HPC3015BM-330M	33.0	0.85	0.75	0.57	0.51	780	940
HPC3015BM-470M	47.0	0.70	0.60	0.46	0.41	1200	1440

Note:

1. Test frequency : Ls : 100KHz /1.0V.
2. All test data referenced to 25℃ ambient.
3. Testing Instrument(or equ) : Agilent 4284A,E4991A,4339B,KEYSIGHT E4980A/AL,chroma3302,3250,16502.
4. Heat Rated Current (Irms) will cause the coil temperature rise approximately ΔT of 40℃
5. Saturation Current (Isat) will cause L0 to drop approximately 30%.
6. The part temperature (ambient + temp rise) should not exceed 125℃ under worst case operating conditions.Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
7. I rms Testing : Temperature rise is highly dependent on many factors including pcb land pattern, trace size, and proximity to other components.
Therefore temperature rise should be verified in application conditions.
8. Rated DC current: The lower value of I rms and Isat.

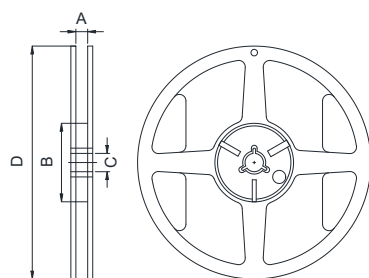
6. Material List



NO	Items	Materials
a	Core	Ferrite Core
b	Wire	Enameled Copper Wire
c	Glue	Epoxy with magnetic powder
d	Terminal	Ag/Ni/Sn+ Sn Solder

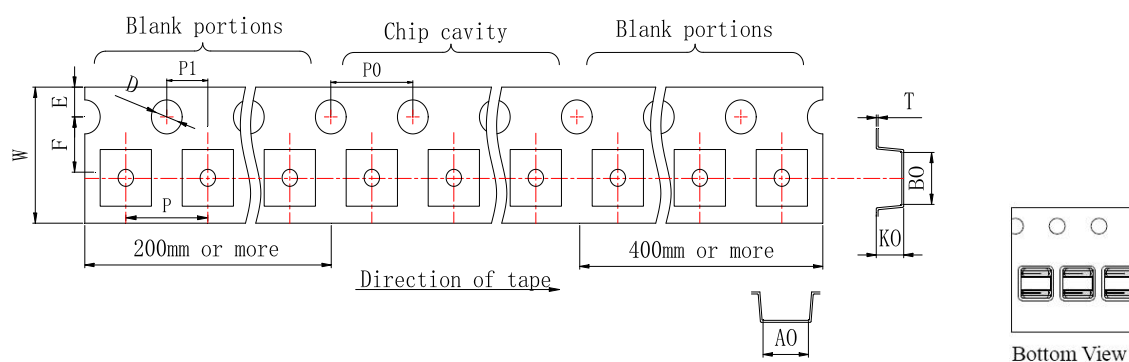
7. Packaging Information

7-1. Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
7" x8mm	8.4+1.5/-0	60±1.0	13+0.5/-0.2	178±2.0

7-2. Tape Dimension



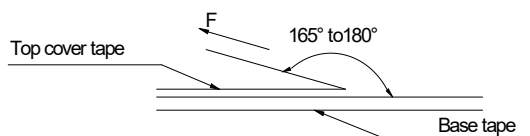
B0	A0	K0	P	W	T	E	F	D	P0	P1
3.4±0.1	3.4±0.1	1.7±0.1	4.0±0.1	8.0±0.3	0.23±0.1	1.75±0.1	3.5±0.1	1.5±0.1	4.0±0.1	2.0±0.1

Unit: mm

7-3. Packaging Quantity

HPC	3015
Reel	2000

7-4. Tearing Off Force

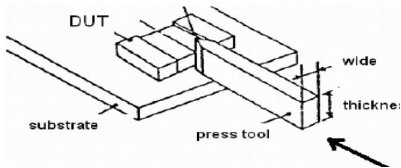


The force for tearing off cover tape is 10 to 100 grams in the arrow direction under the following conditions(referenced ANSI/EIA-481-D-2008 of 4.11 standard).

Tearing Speed mm	Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)
300±10%	5~35	45~85	860~1060

8. Reliability and Test Condition

Item	Performance	Test Condition
Operating temperature	-40~+125℃ (Including self - temperature rise)	
Storage temperature	1. -10~+40℃, 50~60%RH (Product with taping) 2. -40~+125℃ (on board)	
Electrical Performance Test		
Inductance	Refer to standard electrical characteristics list.	HP4284A, CH11025, CH3302, CH1320, CH1320S LCR Meter.
DCR		CH16502, Agilent33420A Micro-Ohm Meter.
Saturation Current (Isat)	Approximately ΔL 30%.	Saturation DC Current (Isat) will cause L0 to drop ΔL (%)
Heat Rated Current (Irms)	Approximately ΔT 40℃	Heat Rated Current (Irms) will cause the coil temperature rise ΔT (℃) without core loss. 1. Applied the allowed DC current. 2. Temperature measured by digital surface thermometer.
Reliability Test		
Life Test	Appearance: No damage. Inductance: within $\pm 10\%$ of initial value. Q: Shall not exceed the specification value. RDC: within $\pm 15\%$ of initial value and shall not exceed the specification value.	Preconditioning: Run through IR reflow for 3 times. (IPC/JEDEC J-STD-020E Classification Reflow Profiles) Temperature: $125 \pm 2^\circ\text{C}$ (Inductor, ambient + temp rise) Applied current: rated current Duration: 1000 ± 12 hrs Measured at room temperature after placing for 24 ± 2 hrs.
Load Humidity		Preconditioning: Run through IR reflow for 3 times. (IPC/JEDEC J-STD-020E Classification Reflow Profiles) Humidity: $85 \pm 2\%$ R.H. Temperature: $85^\circ\text{C} \pm 2^\circ\text{C}$ Duration: 1000hrs Min. Bead: with 100% rated current, Inductance: with 100% rated current Measured at room temperature after placing for 24 ± 2 hrs.
Moisture Resistance		Preconditioning: Run through IR reflow for 3 times. (IPC/JEDEC J-STD-020E Classification Reflow Profiles) 1. Baked at 50°C for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to $65 \pm 2^\circ\text{C}$ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs. 3. Raise temperature to $65 \pm 2^\circ\text{C}$ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs, keep at 25°C for 2 hrs then keep at -10°C for 3 hrs 4. Keep at 25°C 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.
Thermal shock		Preconditioning: Run through IR reflow for 3 times. (IPC/JEDEC J-STD-020E Classification Reflow Profiles) Condition for 1 cycle Step1: $-40 \pm 2^\circ\text{C}$ 30 $\pm$ 5min Step2: $125 \pm 2^\circ\text{C}$ $\cong$ 0.5min Step3: $125 \pm 2^\circ\text{C}$ 30 $\pm$ 5min Number of cycles: 500 Measured at room temperature after placing for 24 ± 2 hrs.
Vibration		Preconditioning: Run through IR reflow for 3 times. (IPC/JEDEC J-STD-020E Classification Reflow Profiles) Oscillation Frequency: 10Hz~2KHz~10Hz for 20 minutes Equipment: Vibration checker Total Amplitude: 10g Testing Time : 12 hours (20 minutes, 12 cycles each of 3 orientations).

Item	Performance	Test Condition														
Bending	Appearance: No damage. Inductance: within±10% of initial value. Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value.	Shall be mounted on a FR4 substrate of the following dimensions: >=0805 inch(2012mm):40x100x1.2mm <0805 inch(2012mm):40x100x0.8mm Bending depth: >=0805 inch(2012mm):1.2mm <0805 inch(2012mm):0.8mm duration of 10 sec.														
Shock		<table><tr><th>Type</th><th>Peak value (g's)</th><th>Normal duration (D) (ms)</th><th>Wave form</th><th>Velocity change (Vi)ft/sec</th></tr><tr><td>SMD</td><td>50</td><td>11</td><td>Half-sine</td><td>11.3</td></tr><tr><td>Lead</td><td>50</td><td>11</td><td>Half-sine</td><td>11.3</td></tr></table> 3 shocks in each direction along 3 perpendicular axes(18 shocks).	Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi)ft/sec	SMD	50	11	Half-sine	11.3	Lead	50	11	Half-sine
Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi)ft/sec												
SMD	50	11	Half-sine	11.3												
Lead	50	11	Half-sine	11.3												
Solderability	More than 95% of the terminal electrode should be covered with solder.	a. Method B1, 4 hrs @155°C dry heat @255°C±5°C Test time:5 +0/-0.5 seconds. b. Method D category 3. (steam aging 8hours ± 15 min)@ 260°C±5°C Test time: 30 +0/-0.5 seconds.														
Resistance to Soldering Heat		Depth: completely cover the termination <table><tr><th>Temperature(°C)</th><th>Time(s)</th><th>Temperature ramp/immersion and emersion rate</th><th>Number of heat cycles</th></tr><tr><td>260 ±5 (solder temp)</td><td>10 ±1</td><td>25mm/s ±6 mm/s</td><td>1</td></tr></table>	Temperature(°C)	Time(s)	Temperature ramp/immersion and emersion rate	Number of heat cycles	260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s	1						
Temperature(°C)	Time(s)	Temperature ramp/immersion and emersion rate	Number of heat cycles													
260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s	1													
Terminal Strength	Appearance: No damage. Inductance: within±10% of initial value. Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value e.	Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles) With the component mounted on a PCB with the device to be tested, apply a force(>0805inch(2012mm):1kg, <=0805inch(2012 mm):0.5kg) to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested. 														

Note : When there are questions concerning measurement result : measurement shall be made after 48 ± 2 hours of recovery under the standard condition.

10. Notes

- (1) When there are questions concerning measurement result : measurement shall be made after 48 ± 2 hours of recovery under the standard condition.
- (2) This power choke coil itself does not have any protective function in abnormal condition such as overload, short-circuit and open-circuit conditions, etc. Therefore, it shall be confirmed as the end product that there is no risk of smoking, fire, dielectric withstand voltage, insulation resistance, etc. in abnormal conditions to provide protective devices and/or protection circuit in the end product.
- (3) When this power choke coil was used in a similar or new product to the original one, sometimes it might not be able to satisfy the specifications due to different condition of use.
- (4) Dielectric withstanding test with higher voltage than specific value will damage insulating material and shorten its life.
- (5) This power choke coil must not be used in wet condition by water, coffee or any liquid because insulation strength becomes very low in this condition.
- (6) Please consult our company to confirm the reliability of the process required to wash or use or exposure to a chemical solvent used in this product. PCB washing tested to MIL-STD-202 Method, and dry it off immediately.
- (7) The rated current as listed is either the saturation current or the heating current depending on which value is lower.
- (8) If this power choke is dipped in the cleaning agent, such as toluene, xylene, ketone, and ether system, there is a possibility that the performance decreases greatly, and marking disappears.
- (9) The high power ultrasonic washing may damage the choke body.
- (10) Before use, the user should determine whether this product is suitable for their own design, Our company only guarantees that the product meets the requirements of this specification.

Application Notice

· Storage Conditions

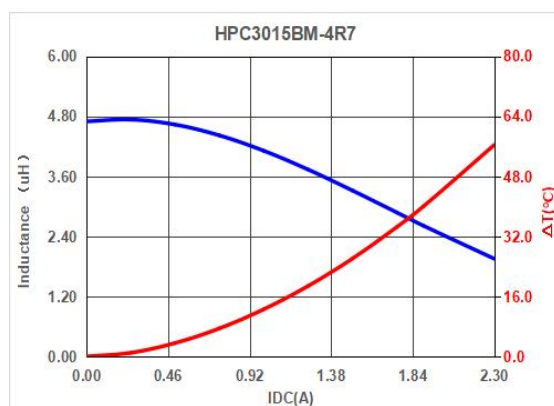
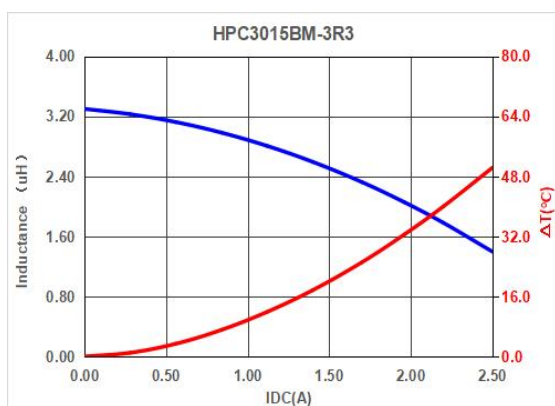
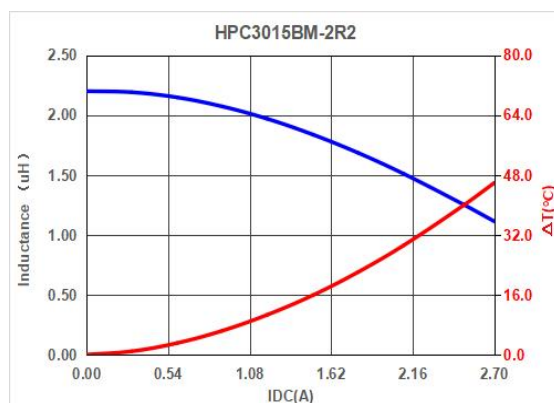
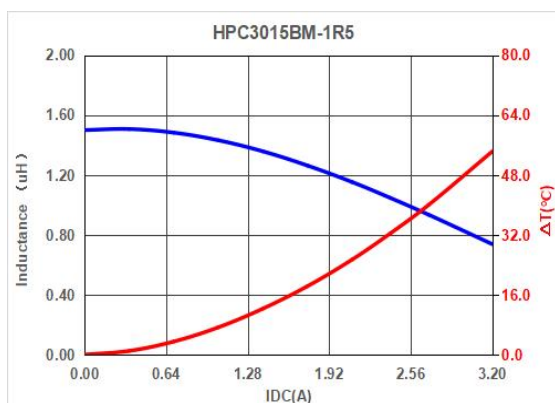
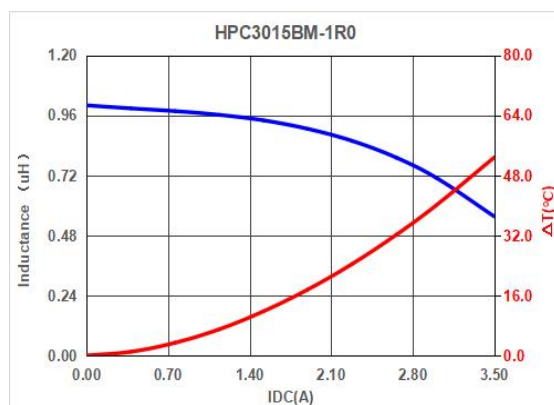
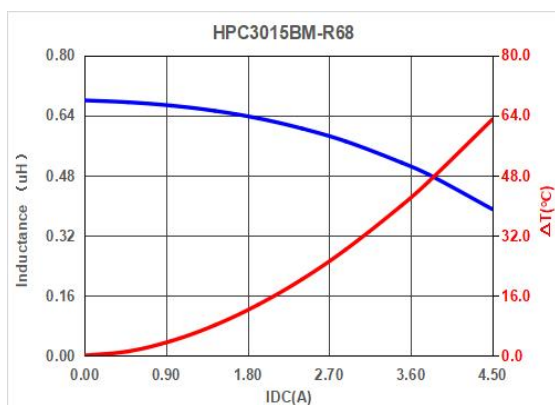
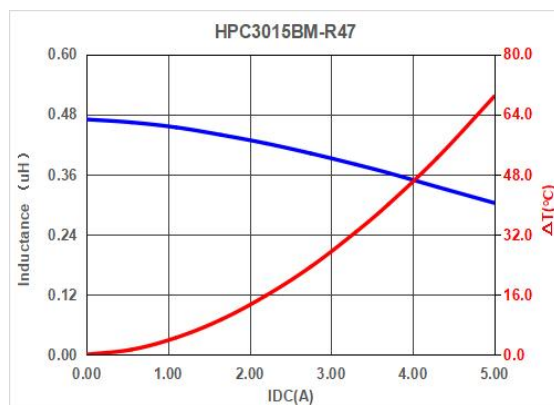
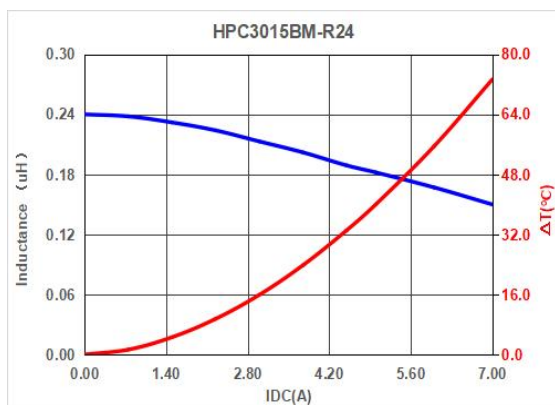
To maintain the solderability of terminal electrodes:

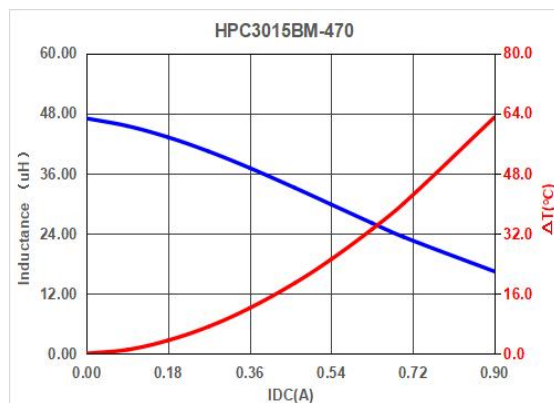
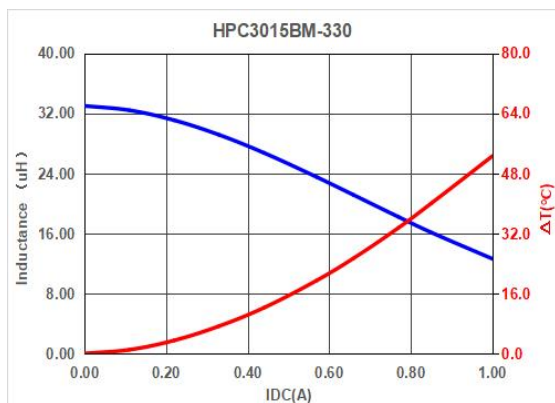
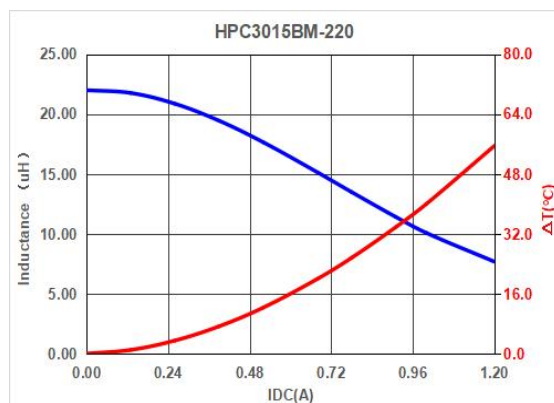
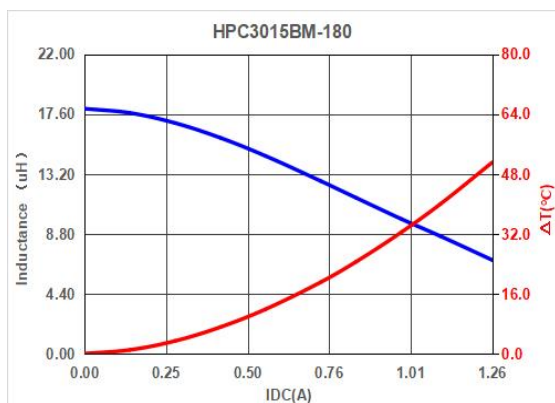
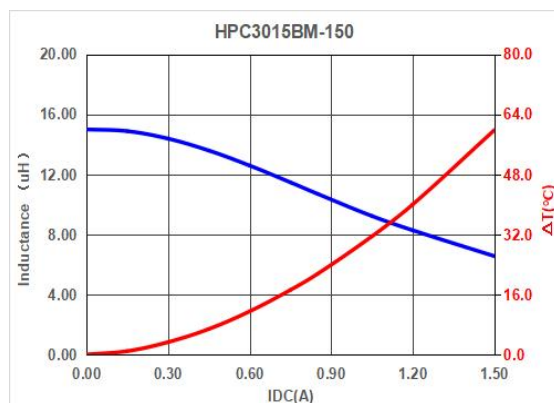
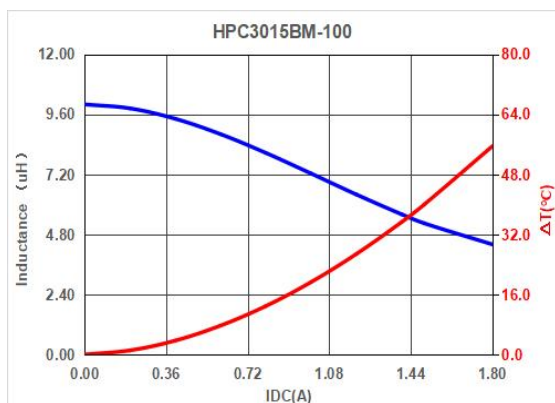
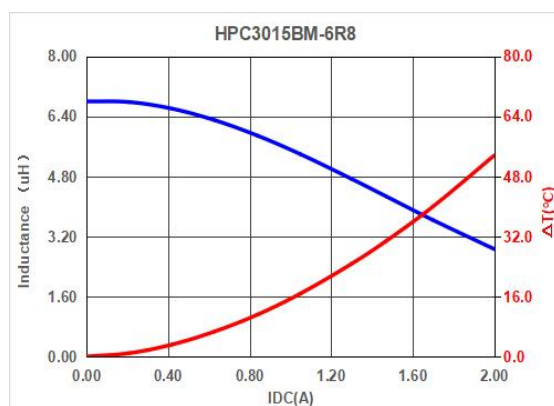
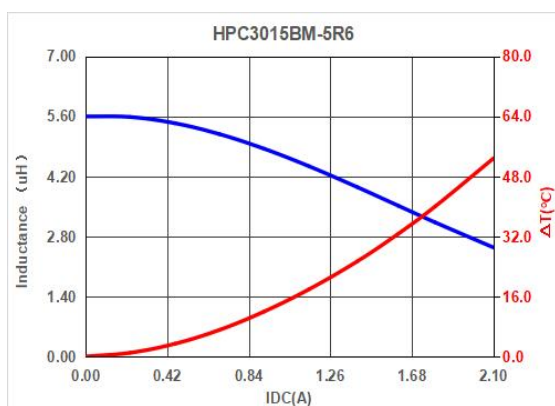
1. TAI-TECH products meet IPC/JEDEC J-STD-020E standard-MSL, level 1.
2. Temperature and humidity conditions: Less than 40℃ and 85% RH.
3. Recommended products should be used within 12 months from the time of delivery.
4. The packaging material should be kept where no chlorine or sulfur exists in the air.

· Transportation

1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

11. Typical Performance Curves

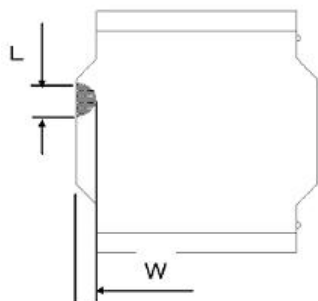




12. Appearance criterion

12-1. Core chipping

The appearance standard of the chipping size on top side, and bottom side ferrite core is listed below.
 Chip off is generated during molding and manufacturing process.
 Chip off acceptance limits subjected to the product size.
 Our current Defect limit is based on the IPC-A-610.
 Some chip off does not impact the product function, see the IPC standard 1 & 2.

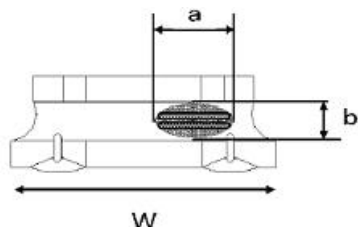


L	$\leq 50\%$ of the length
W	$\leq 25\%$ of the width

Defects usually occur at the corners and edges of the product, There will be a slight defect black and rough, but not exposed copper, and does not affect the product performance and reliability.

12-2. Void appearance tolerance Limit

Size of voids occurring to coating resin is specified below.



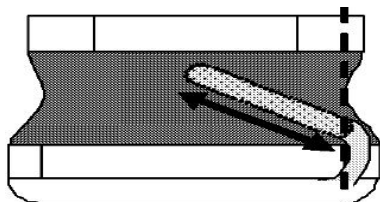
Exposed wire tolerance limit of coating resin part on product side.

Size of exposed wire occurring to coating resin is specified below.

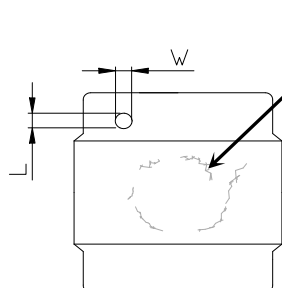
1. Width direction (dimension a): Acceptable when $a \leq w/2$.
2. Length direction (dimension b): Dimension b is not specified.
3. The total area of exposed wire occurring to each sides is not greater than 50% of coating resin area, and is acceptable.

12-3. External appearance criterion for exposed wire

Exposed winding wire at the secondary side is regarded as qualified product.



12-4. Electrode appearance criterion for exposed wire



Visual check on core surface with no crack means pass.

Only top side of wire is exposed.
 (regardless of whole top side of wire exposed)

Conforming

Wire is soldered insufficiently and less than half of outer diameter is covered with solder.

Less than 1/2 of joint side length.
 (More than 1/2 is selected as defect)

L&w
$\leq 20\%$ of the area on one single pad

Foreign materials on the product body is inevitable and accepted.
 Electrodes with foreign body (dirt) appearance standards
 Foreign materials (dirt) will not affect the coplanarity of PAD,
 below the example of foreign materials (dirt) quantity ≤ 2 PCS on single PAD.
 Dimensions range as shown in the table.